



VN67 SERIES

N-Channel Enhancement-Mode MOS Transistors

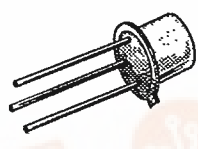
PRODUCT SUMMARY

PART NUMBER	V _{(BR)DSS} (V)	r _{DS(ON)} (Ω)	I _D (A)	PACKAGE
VN67AB	60	3.5	0.79	TO-205AD
VN67AD	60	3.5	1.58	TO-220
VN67AFD	60	3.5	1.37	TO-220SD

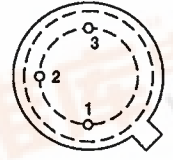
Performance Curves: VNDQ06 (See Section 7)

T-39-05

TO-205AD (TO-39)



BOTTOM VIEW



- 1 SOURCE
- 2 GATE
- 3 DRAIN & CASE

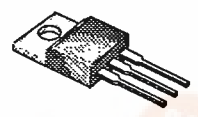
TO-220

- 1 GATE
- 2 & TAB - DRAIN
- 3 SOURCE

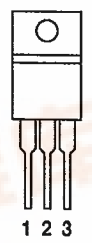
TO-220SD

- 1 SOURCE
- 2 GATE
- 3 & TAB - DRAIN

TO-220/TO-220SD



TOP VIEW



ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)²

PARAMETERS/TEST CONDITIONS		SYMBOL	VN67AB	VN67AD	VN67AFD	UNITS
Drain-Source Voltage		V _{DS}	60	60	60	V
Gate-Source Voltage		V _{GS}	±20	±30	±30	
Continuous Drain Current	T _C = 25°C	I _D	0.79	1.58	1.37	A
	T _C = 100°C		0.5	1	0.87	
Pulsed Drain Current ¹		I _{DM}	3	3	3	
Power Dissipation	T _C = 25°C	P _D	5	20	15	W
	T _C = 100°C		2	8	6	
Operating Junction and Storage Temperature		T _J , T _{stg}	-55 to 150			°C
Lead Temperature (1/16" from case for 10 seconds)		T _L	300			

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THERMAL RESISTANCE

THERMAL RESISTANCE	SYMBOL	VN67AB	VN67AD	VN67AFD	UNITS
Junction-to-Case	R _{thJC}	25	6.25	8.3	°C/W

¹Pulse width limited by maximum junction temperature
²Absolute maximum ratings have been revised from previous data sheet



VN67 SERIES

T-39-05



ELECTRICAL CHARACTERISTICS ¹				LIMITS		
PARAMETER	SYMBOL	TEST CONDITIONS ⁴	TYP ²	VN67 ⁴		UNIT
				MIN	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 10\ \mu\text{A}$	70	60		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1\text{ mA}$	1.5	0.8	2.5	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$ $V_{GS} = \pm 15\text{ V}$ $T_C = 125^\circ\text{C}$	± 1 ± 5		± 100 ± 500	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}$ $V_{DS} = 60\text{ V}$ $V_{DS} = 48\text{ V}, T_C = 125^\circ\text{C}$	0.05 0.3		10 500	μA
On-State Drain Current ³	I_D	$V_{DS} = 10\text{ V}, V_{GS} = 10\text{ V}$	1.8	1.5		A
Drain-Source On-Resistance ³	$r_{DS(on)}$	$V_{GS} = 5\text{ V}, I_D = 0.3\text{ A}$	1.8		5	Ω
		$V_{GS} = 10\text{ V}$ $I_D = 1\text{ A}$ $T_C = 125^\circ\text{C}$	1.3 2.6		3.5 7	
Forward Transconductance ³	g_{FS}	$V_{DS} = 10\text{ V}, I_D = 0.5\text{ A}$	350	170		mS
Common Source Output Conductance ³	g_{OS}	$V_{DS} = 7.5\text{ V}, I_D = 0.1\text{ A}$	1100			μS
DYNAMIC						
Input Capacitance	C_{iss}	$V_{DS} = 25\text{ V}$ $V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$	35		50	pF
Output Capacitance	C_{oss}		25		40	
Reverse Transfer Capacitance	C_{rss}		5		10	
SWITCHING						
Turn-On Time	t_{ON}	$V_{DD} = 25\text{ V}, R_L = 23\ \Omega$ $I_D = 1\text{ A}, V_{GEN} = 10\text{ V}, R_G = 25\ \Omega$ (Switching time is essentially independent of operating temperature)	8		15	ns
Turn-Off Time	t_{OFF}		9.5		15	

- NOTES: 1. $T_C = 25^\circ\text{C}$ unless otherwise noted.
 2. For design aid only, not subject to production testing.
 3. Pulse test; $PW = 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
 4. Data sheet limits and/or test conditions have been revised.